

High-Quality, Ultra-Thin Dielectric Integration on Graphene Enabled by Plasma ALD

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The performance potential of nanoelectronic devices based on two-dimensional (2D) materials remains largely unexplored due to the lack of scalable, high-quality insulators¹. In this presentation, we propose a scalable approach for the deposition of high-quality dielectric on graphene. In previous year, we introduced an in-situ damage-free dielectric deposition process utilising a nonstoichiometric AIOX seed layer grown under mild plasma conditions² (see Figure 1a and b). In this presentation, we demonstrate the effectiveness of this approach on top-gated graphene field-effect transistors (GFETs). Dual-gate measurement devices fabricated using our method achieve an equivalent oxide thickness (EOT) below 5 nm (Figure 1c and d) and an electric field strength exceeding 11 MV/cm (Figure 1e) on a wafer scale. Additionally, we will discuss the impact of in-situ cleaning and post-deposition annealing on device performance, highlighting the potential of this method for other 2D materials and alternative dielectric systems.

This work has received funding from the European Union's Horizon Europe research and innovation program under grant agreement 952792 (2D-EPL) and 101189797 (2D-PL).

References

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- [2] H. Knoop et al., J. Vac. Sci. Technol. A, 39 (2021) 062403

Figures

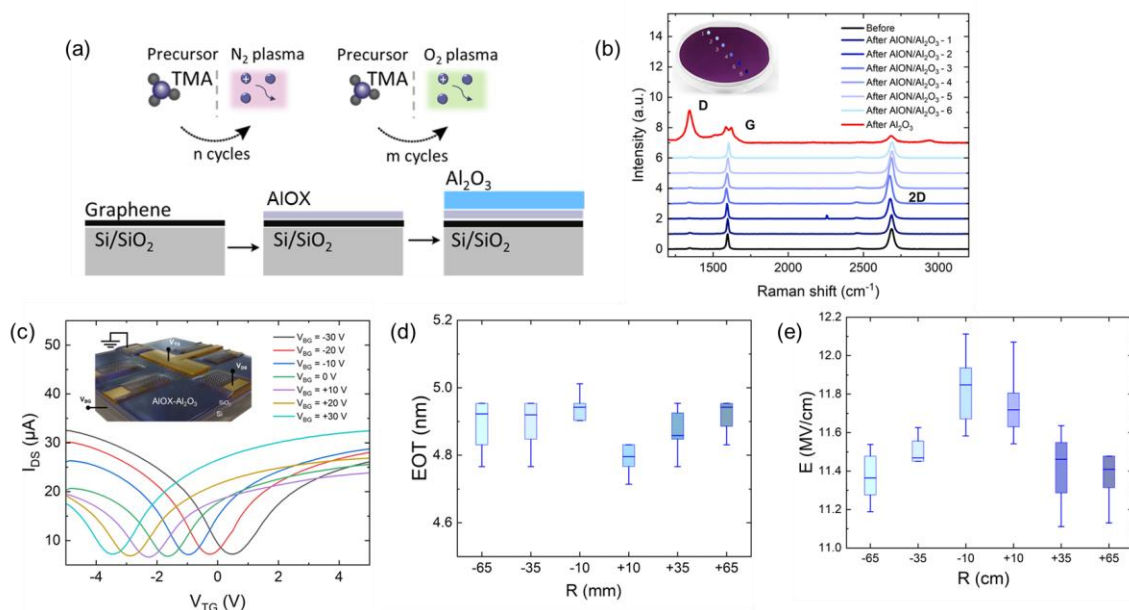


Figure 1: (a) Process scheme of AIOX seed-layer deposition and Al₂O₃ plasma ALD. (b) Raman spectra across the wafer radius (R) for Gr/SiO₂/Si wafers before (black) and after Al₂O₃ deposition without (red) and with (blue) AIOX seed-layer. (c) Dual-gated current–voltage plots for a GFET. Inset: Schematic of a dual-gated GFET in a two-point measurement. Statistical extraction of (d) EOT and (e) the electric field strength over R.